

In the Specification

At page 1, after the title insert:

CROSS REFERENCE TO RELATED APPLICATION

This is a Division of U.S. Patent Application Serial No. 09/148,723, filed September 3, 1998, entitled "Methods of Bonding Solder Balls to Bond Pads on a Substrate".

In the Claims

Cancel claims 1-3.

4. (Amended) The method of bonding solder balls of claim 12, wherein said placing comprises placing individual solder balls within individual holes within the frame.

5. (Amended) The method of bonding solder balls of claim 12, wherein said placing comprises placing majority portions of individual solder balls within individual holes within the frame.

6. (Amended) The method of bonding solder balls of claim 12, wherein said exposing comprises laser bonding the balls with their associated bond pads.